





- See yesterday Daniel's talk
- Most probably:
  - 45° tower
  - Slide ~20 cm into the structure : long adapter board
- Thickness of the alveola to be determined
  - Lower the risks of not being able to slide a SLAB
    - Thickness of the resin+thermal paste above the chip
    - Copper sheet could be cut
  - Add 500-1000 um would allow to comply with most of the variants and options
    - U
    - Standard H
    - Thicker H
  - Then start with existing HW ('U' slab) and follow tech. progress (and available money)
    - Poor thickness optimization wrt physics